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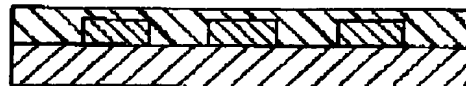
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TITLE : RESIN COMPOSITION AND METHOD
FOR FORMING MULTILAYER
INTERCONNECTION

ABSTRACT : PROBLEM TO BE SOLVED: To provide a material which can be applied by spin coating, is liquefied at relatively low temps. thus being able to become flat in the chip scale, can be formed into a film by the spin coating method capable of gap filling. and can provide a thermally cured insulating film having a permittivity of 2.5 or lower and to provide a method for forming such an insulating film.

SOLUTION: This resin compsn. for forming a multilayer interconnection comprises a high-molecular substance which can be thermally liquefied and cross-linked to become insol. and a silica sol or comprises a binder resin and fine tetrafluoroethylene polymer particles. The compsn. is applied onto a wiring board and thermally treated to form a flat insulating film.

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